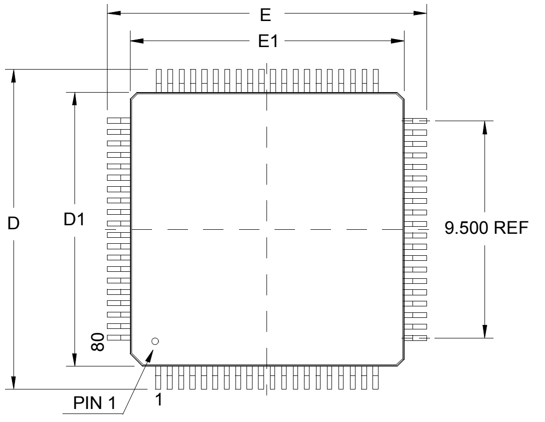
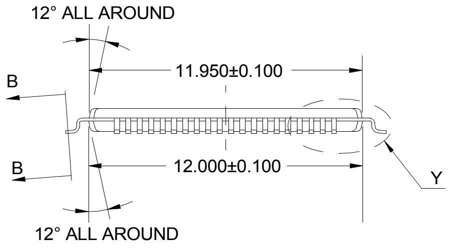
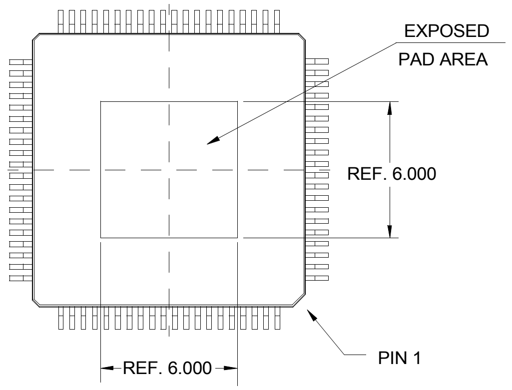
Thin Plastic Quad Flatpack Exposed Pad Packages (EPTQFP)



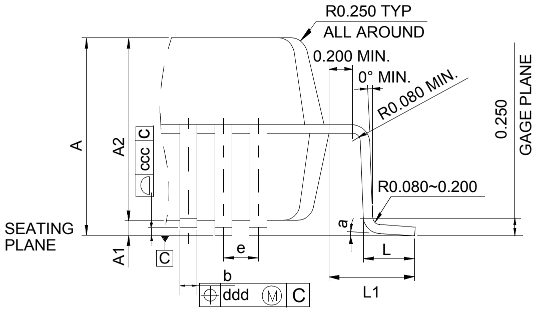
TOP VIEW



SIDE VIEW



BOTTOM VIEW



DETAIL "Y"

Q80.12x12

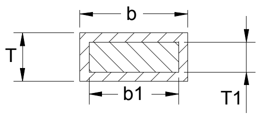
80 LEAD THIN PLASTIC QUAD FLATPACK EXPOSED PAD PACKAGE

SYMBOL	MILLIMETERS			REMARKS
	MIN	TYP	MAX	
A	-	-	1.20	Overall height
A1	0.05	0.10	0.15	Standoff
A2	0.90	1.00	1.10	Package thickness
D	13.8	14.0	14.2	Lead tip to tip
D1	11.9	12.0	12.1	Package length
E	13.8	14.0	14.2	Lead tip to tip
E1	11.9	12.0	12.1	Package width
L	0.45	0.60	0.75	Foot length
L1	1.000 REF.			Lead length
T	0.09	0.150	0.20	Lead thickness
T1	0.097	0.127	0.157	Lead base metal thickness
a	0°~7°			Foot angle
b	0.17	0.22	0.27	Lead width
b1	0.17	0.20	0.23	Lead base metal width
e	0.500 BASE			Lead pitch
ccc	-	0.080	-	Foot coplanarity
ddd	-	0.080	-	Foot position

Rev. 0 8/07

NOTES:

1. General tolerance. Distance: ±0.1000, Angle: ±2.5°
2. Matte finish on package body surface except ejection and pin 1 marking: Ra0.8~2.0um
3. All molded body sharp corner radii unless otherwise specified: MAX. R0.200
4. Package/lead frame misalignment (X, Y): MAX. 0.127
5. Top/bottom package misalignment (X, Y): MAX. 0.127
6. Drawing does not include plastic or metal protrusion or cutting burr.
7. Compliant to JEDEC standard MS-026.



SECTION B-B